

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2674978

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SON-YOUNG LEE</td> <td>11/25/2013</td> </tr> <tr> <td>WON-SUK CHUNG</td> <td>11/25/2013</td> </tr> <tr> <td>JUN-SE KIM</td> <td>11/25/2013</td> </tr> <tr> <td>SANG-WON YOON</td> <td>11/25/2013</td> </tr> </tbody> </table>		Name	Execution Date	SON-YOUNG LEE	11/25/2013	WON-SUK CHUNG	11/25/2013	JUN-SE KIM	11/25/2013	SANG-WON YOON	11/25/2013
Name	Execution Date										
SON-YOUNG LEE	11/25/2013										
WON-SUK CHUNG	11/25/2013										
JUN-SE KIM	11/25/2013										
SANG-WON YOON	11/25/2013										
RECEIVING PARTY DATA											
Name:	Samsung Electronics Co. Ltd.										
Street Address:	129, Samsung-ro										
Internal Address:	Yeongtong-gu										
City:	Suwon-si, Gyeonggi-do										
State/Country:	KOREA, REPUBLIC OF										
Postal Code:	443-742										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>29457870</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	29457870						
Property Type	Number										
Application Number:	29457870										
CORRESPONDENCE DATA											
Fax Number:	(513)241-6234										
Phone:	5132412324										
Email:	khoward@whe-law.com										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	WOOD, HERRON & EVANS, LLP										
Address Line 1:	441 VINE STREET										
Address Line 2:	SUITE 2700										
Address Line 4:	CINCINNATI, OHIO 45202										
ATTORNEY DOCKET NUMBER:	SMSG-178										
NAME OF SUBMITTER:	KATHERINE HOWARD										

Signature:	/katherine howard/
Date:	01/09/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
<b>Total Attachments: 3</b> source=SMSG-178 FD-1767-Declaration&Assignment#page1.tif source=SMSG-178 FD-1767-Declaration&Assignment#page2.tif source=SMSG-178 FD-1767-Declaration&Assignment#page3.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN  
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention: Body of portable computer

As the below named inventor, I hereby declare that:

This Declaration is directed to the attached application;

The above-identified application was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

Whereas, the undersigned inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application;

Whereas, **SAMSUNG ELECTRONICS CO., LTD.**, a corporation of the country of **REPUBLIC OF KOREA**, having a place of business at **129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 443-742, Republic of Korea** (herein referred to as the "ASSIGNEE"), desires to acquire, and each undersigned inventor desires to grant to the **ASSIGNEE**, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

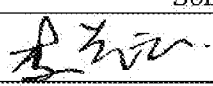
Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor ("ASSIGNOR") hereby sells or has sold, assigns or has assigned, and otherwise transfers or has transferred to the **ASSIGNEE**, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to the **ASSIGNEE**, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by the **ASSIGNEE**, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had

this Assignment not been made; and each undersigned inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in the **ASSIGNEE**, its successors, legal representatives, and assigns, whenever requested by the **ASSIGNEE**, its successors, legal representatives, or assigns.

Each undersigned inventor acknowledges his/her prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to the **ASSIGNEE** and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned inventor also hereby grants the **ASSIGNEE**, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent Application Number) which may be necessary or desirable for recordation of this Assignment.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Legal name of  
Inventor: Son-Young LEE

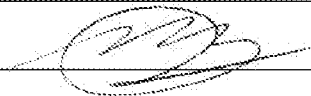
Inventor's Signature:  Date: Nov. 25, 2013

Residence  
City/State/Country: Seoul, Korea

Mailing Address: 301, The house 4 cha, 16, Seoulsiripdae-ro 25-gil, Dongdaemun-gu, Seoul, Korea

Citizenship: Republic of Korea

Legal name of  
Inventor: Won-Suk CHUNG

Inventor's Signature:  Date: Nov 25, 2013

Residence  
City/State/Country: Seoul, Korea

Mailing Address: 204-101, Hyundai APT., 69, Apgujeong-ro 29-gil, Gangnam-gu, Seoul, Korea

Citizenship: Republic of Korea

Legal name of  
Inventor: Jun-Se KIM

Inventor's Signature:  Date: 2013.11.25

Residence  
City/State/Country: Seoul, Korea

Mailing Address: 311, Libero officetel, 82, Gwancheon-ro, Gwanak-gu, Seoul, Korea

Citizenship: Republic of Korea

Legal name of  
Inventor: Sang-Won YOON

Inventor's Signature:  Date: 2013.11.25

Residence  
City/State/Country: Seoul, Korea

Mailing Address: 103-1401, Seocho Samsung Raemian, 116, Saimdang-ro 17-gil,  
Seocho-gu, Seoul, Korea

Citizenship: Republic of Korea